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25. (amended) The method of claim 24, wherein a first set of one or more of the intermediate layers are silicon, and a second set of one or more of the intermediate layers comprise the first metal, the first set of layers and the [set] second set of layers being deposited in alternating fashion.

REMARKS

Claims 1 - 30 and 36 - 40 are still pending in this application and have been rejected by Examiner.

1. Applicants amended the specification on page 14 to simplify the public's ability to find Applicants' list of silicates. These silicates were listed on page 6, lines 15 - 19, but are now also included near the discussion of preferred qualities. Applicants do not claim that this list is an exhaustive recital of all metal silicate dielectrics—but do believe that they give appropriate initial guidance to skilled artisans.

2. Regarding the 35 U.S.C. § 112, first paragraph rejection, Applicants believe that the focussed teaching on page 6, lines 15 - 19 describes a number of metal silicates in such a way as to enable skilled artisans to make and use the invention.

3. Applicants respectfully traverse the 35 U.S.C. § 103 rejections over Wu (Wu '353), in view of Hsieh *et al.* (Hsieh '035), and—for some claims—Gardner *et al.* (Gardner '921). Wu '353 was filed on October 20, 1997. Applicants application includes a claim for priority from U.S. provisional application 60/053,661, filed 7/24/97. The Office Action stated that 60/053,661 met the requirements for domestic priority.

Since the 60/053,661 priority date is before the filing date of Wu '353, Applicants submit that Wu '353 is not a proper reference for a 35 U.S.C. § 103 rejection. Applicants request allowance of Claims 1 - 30 and 36 - 40, since the remaining references—taken together—do not suggest the claimed invention to one of ordinary skill in the art.

If Examiner has any further comments or suggestions, Applicants respectfully request that Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

Respectfully submitted,



David Denker
Reg. No. 40,987

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-4388
Fax (972) 917-4418